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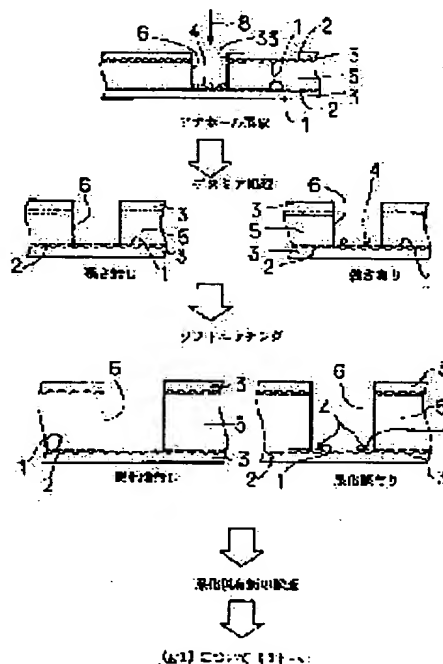
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(54) PRINTED WIRING BOARD AND ITS MANUFACTURE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a printed wiring board with via holes having high continuity reliability and a method for manufacturing the board.
SOLUTION: After a blackened film 1 is formed by blackening metal foil 3, the metal foil 3 is stuck to the bottom of the via hole-forming section of an insulating substrate 5 in a state where the blackened film 1 is faced to the bottom. Then a via hole 6 bottomed with the metal foil 3 is formed by irradiating the substrate 5 with a laser beam 8 and desmearing treatment is performed on the foil 3 exposed at the bottom of the via hole. In addition, soft etching is performed on the plated metallic film exposed at the bottom of the via hole. Thereafter, a plated metallic film is formed in the via hole after confirming that the blackened film 1 is removed by the soft etching from the surface of the foil 3 at the bottom of the via hole and a conductor pattern is formed by etching the foil 3.



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